

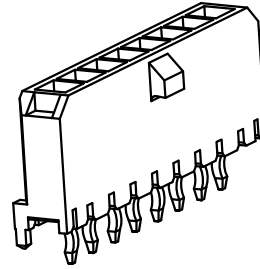
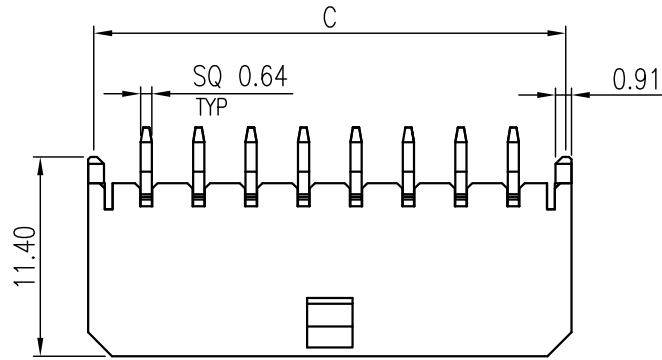
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The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.



ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14198	RELEASE FOR RoHS	11/06/2014	Arron Lin
B	NE-17058	UPDATED PACKAGING QUANTITY	03/24/2017	Roger Tsai



NOTE:

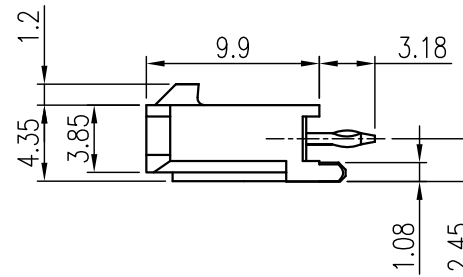
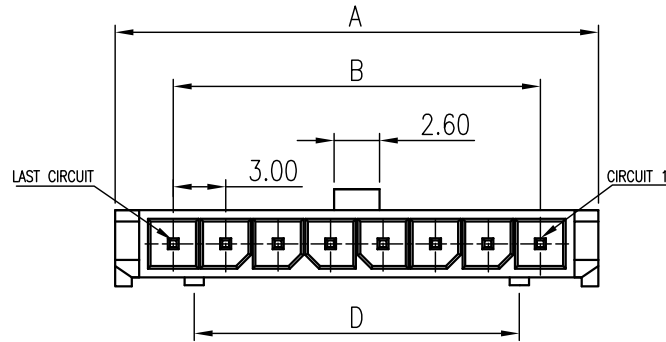
- INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR: BLACK.
- CONTACT MATERIAL: COPPER ALLOY;
- FINISH:  
CONTACT: SELECTIVE PLATING;  
SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;  
UNDER PLATING: NICKEL PLATING 50 u" THICKNESS MIN. OVERALL.
- THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
- PACKING MUST BE PER Amphenol PACKING SPECIFICATION

PART NO. G881BXX1X2KEU

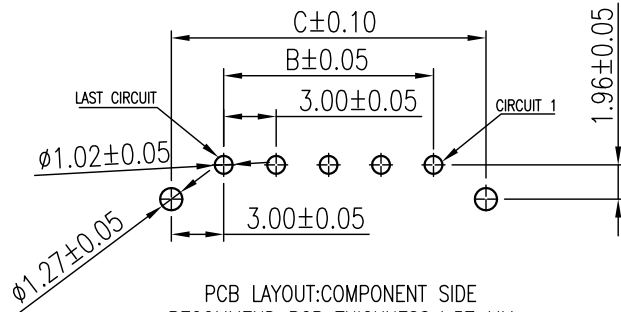
No. OF CIRCUIT

CONTACT FINISH

- 0: Tin (OVERALL)
- 1: FLASH GOLD (OVERALL)
- 2: 15 u" GOLD
- 3: 30 u" GOLD



12	39.65	33.00	39.0	30.6
11	36.65	30.00	36.0	27.6
10	33.65	27.00	33.0	24.6
09	30.65	24.00	30.0	21.6
08	27.65	21.00	27.0	18.6
07	24.65	18.00	24.0	15.6
06	21.65	15.00	21.0	12.6
05	18.65	12.00	18.0	9.6
04	15.65	9.00	15.0	6.6
03	12.65	6.00	12.0	1.9
02	9.65	3.00	9.0	1.9
POS	A	B	C	D



PCB LAYOUT: COMPONENT SIDE  
RECOMMEND PCB THICKNESS: 1.57 MM

TOLERANCE	APPROVALS	DATE	TITLE		PART No.	
X. ±0.30	DRAWN Aqua Chou	03/24/2017	G881B SERIES MICRO POWER WAFER 3.00 MM PITCH STRAIGHT S/R W/KINK TYPE		<b>Amphenol</b> ® Amphenol Corporation Amphenol Taiwan Corporation	
X.X ±0.20	CHECKED Roger Tsai	03/24/2017				
X.XXX ±0.10	APPROVED Roger Tsai	03/24/2017				
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	PART No. G881BXX1X2KEU	
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 1 OF 3	DWG No. G881BXX1X2KEU REV. B	

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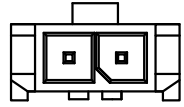
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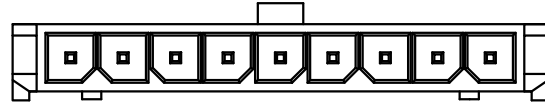
ORIGINAL



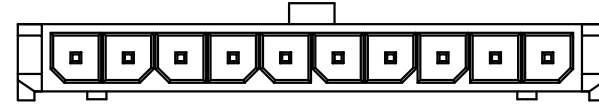
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
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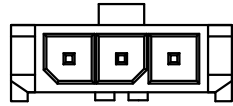
2 POS



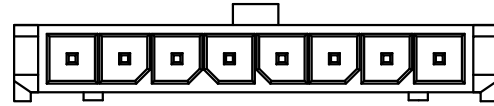
9 POS



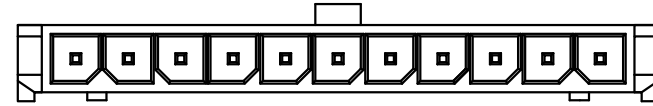
10 POS



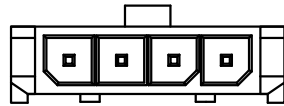
3 POS



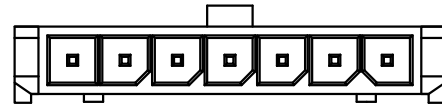
8 POS



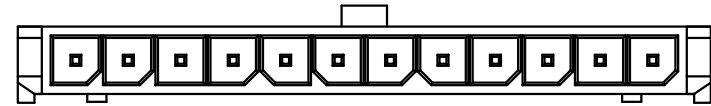
11 POS



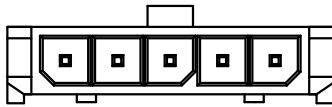
4 POS



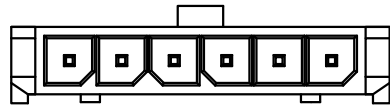
7 POS



12 POS



5 POS



6 POS

TOLERANCE		APPROVALS		DATE	<b>TITLE</b> G881B SERIES MICRO POWER WAFER 3.00 MM PITCH STRAIGHT S/R W/KINK TYPE			<b>Amphenol</b> ® Amphenol Corporation Amphenol Taiwan Corporation					
X.		DRAWN	Aqua Chou	03/24/2017				UNIT	mm	SIZE	A3	PART No.	G881BXX1X2KEU
X.X	±0.30	CHECKED	Roger Tsai	03/24/2017				SCALE	NA	SHEET	2 OF 3	DWG No.	G881BXX1X2KEU
X.XX	±0.20	APPROVED	Roger Tsai	03/24/2017								REV.	B
X.XXX	±0.10	DWG TYPE	CUST DWG	PROJECT CODE				PHD					
ANGULAR ±1°		UNLESS OTHERWISE SPECIFIED											

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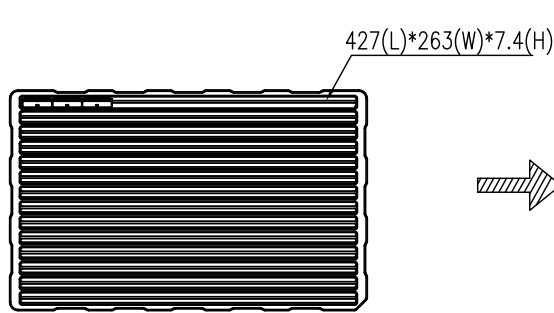
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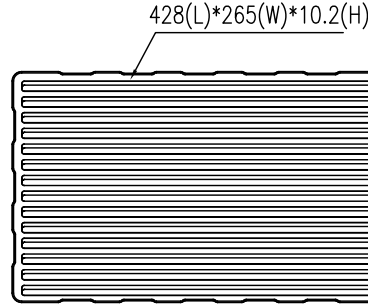
ORIGINAL



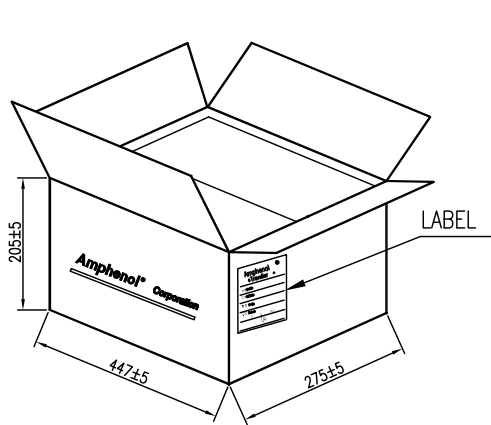
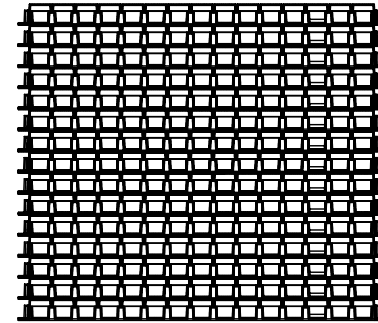
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TRAY BOTTOM COVER



TRAY TOP COVER



(15 TRAYS / CARTON)

POS	PCS/TRAY	PCS/CARTON
2	615	7380
3	465	5580
4	375	4500
5	315	3780
6	270	3240
7	240	2880
8	210	2520
9	195	2340
10	165	1980
11	150	1800
12	135	1620

TOLERANCE		APPROVALS		DATE		TITLE		PART No.			
X.		DRAWN	Aqua Chou		03/24/2017	G881B SERIES MICRO POWER WAFER 3.00 MM PITCH STRAIGHT S/R W/KINK TYPE		Amphenol <sup>®</sup> Amphenol Corporation Amphenol Taiwan Corporation			
X.X	±0.30	CHECKED	Roger Tsai		03/24/2017						
X.XX	±0.20	APPROVED	Roger Tsai		03/24/2017						
X.XXX	±0.10					UNIT	mm	SIZE	A3		
ANGULAR	±1°	DWG TYPE		PROJECT CODE		SCALE	NA	SHEET	3 OF 3		
UNLESS OTHERWISE SPECIFIED		CUST DWG		PHD				DWG No.	G881BXX1X2KEU	REV.	B